**1**<sup>st</sup> Open Meeting of the SuperKEKB Collaboration

# **DSSD R&D Progress at KNU**

**HyoJung Hyun**, DongHa Kah, Youngim Kim, Hyunok Kim, Hongjoo Kim, and Hwanbae Park Kyungpook National University

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#### <100> high resistivity ,n-type, 6 in. 400 µm thick wafer



<100> high resistivity ,n-type, 5 in. 380 µm thick wafer

## **AC-SSSD : Prototypes**



## AC-SSSD : Source test with <sup>90</sup>Sr



![](_page_3_Figure_2.jpeg)

Pedestal : 1549.73 ± 15.17 Signal (MPV) : 1882.67 → SNR = 21.94

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![](_page_4_Figure_0.jpeg)

### **DC-DSSD : Electrical characteristics**

![](_page_5_Figure_1.jpeg)

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## **Specification**

AC-SSSD			DC-DSSD	
380		Thickness (μm)	380	
35000  imes 28000		Area (μm²)	$55610 \times 29460$	
type 1	type2	Number of string	p+ side	n+ side
128	256	Number of strips	512	512
200	100	Strip pitch (μm)	100	50
200	100	Readout pitch (µm)	50	50
80	40	Strip width (μm)	9	9
500		SiO <sub>2</sub> layer thickness (nm)		
~ 25		target biasing resistance (M $\Omega$ )		
~ 150		target coupling capacitance (pF)		
	Good	AC-I	<b>J</b> 33D	

## AC-DSSD

- SuperB Silicon Vertex Detector (LOI' 04)
  - Inner 2-layer PXD / Outer 4-layer DSSD

![](_page_7_Picture_3.jpeg)

Total 14 photo-masks are needed to fabricate the sensor.

![](_page_7_Figure_5.jpeg)

## **AC-DSSD : Prototype**

- 5inch wafer
  - <100> 5kΩ•cm N type
  - thickness : 380µm
- 3 type strip sensors
  - size : 2.8cm × 2.8cm
  - A,B,C type has the 256/512 strips, coupling capacitor and bias resistor
  - B and C type have VIA structure for same read-out direction (N and P)
  - E type is DC sensor
- 3 type Pixel sensors
  - AC Pixel array
    - 11 × 11 array D type
  - DC pixel array
    - 11 × 11 array E\_Pix type
    - 11 × 22 array E\_Pix\_x2 type 1st Open Meeting of the SuperKEKB Collaboration, KEK, Japan, 10-12 December, 2008

![](_page_8_Figure_15.jpeg)

## **AC-DSSD : Specification**

	AC			DC		
туре	А	В	С	Е		
size	2.8 cm × 2.8 cm					
number of channels	256	256	512	256		
strip pitch (μm)	100	100	50	100		
strip width (μm)	40	40	10	40		
P-stop punch-through space (μm)	6	6	6	6		
Biasing resistance expected value (MΩ)	11.88	11.88	12.88	-		
coupling capacitance expected value (pF)	212.06	212.06	61.85	-		
VIA structure for same readout direction	w/o	w/	w/	w/o		
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## **AC-DSSD : detailed view of C-type**

![](_page_10_Picture_1.jpeg)

## **AC-DSSD : Electrical characteristics**

![](_page_11_Figure_1.jpeg)

- Leakage current and bulk capacitance of AC-DSSD is about 5 μA and 95 pF at around 70 V, respectively.
- Bias resistor : target value is 12 M $\Omega$  , and measured values are about 11 M $\Omega$  (5 M $\Omega$ ) for p-side (n-side).
- Coupling capacitance : target value is 200 pF, measured value is about 140 pF for both sides.

## **Readout Electronics**

![](_page_12_Figure_1.jpeg)

![](_page_12_Picture_2.jpeg)

- Sensor board
  - DC DSSD
  - Discrete RCs
- VATA board
  - multiplexed analogue readout
  - common wire-or'ed trigger output
- DAQ board
  - FADC chip
  - Xilinx chip
  - Ethernet Interface

Readout Electronics(preliminary test result)

 Entres
 9822

 Mean
 1641

 RM5
 29.68

  $\chi^2$  / ndf
 245.2 / 90

 Constant
 503.9 ± 6.6

 Mean
 1664 ± 6.2

 Sigma
 22.75 ± 0.19

![](_page_13_Figure_1.jpeg)

- VATA Calibration
  - 1 ADC count = 43 electrons

#### Pedestal

- ENC(VATA) ~ 480 e- rms
- ENC(p-side+VATA) ~ 1000 e- rms
- ENC(n-side+VATA)  $\sim$  1000 e- rms
- Coincidence between p and n sides works well

## **Summary and Plan**

- We've got experience of development of various sensors.
  - Strip sensor with DSSD and Integrated capacitive readout coupling, AC-SSSD
  - also we designed and fabricated pixel array sensors
- We have a ability to fabrication of good quality sensors.
- AC-DSSDs are being fabricated. Electrical characteristics were measured and the second batch is being processed based on the measurement results.
- A radioactive source test is planned.

![](_page_15_Picture_0.jpeg)

# Extra page

## **AC-SSSD : Electrical characteristics**

![](_page_16_Figure_1.jpeg)

![](_page_17_Figure_0.jpeg)

 $\sim 5~\mu A$  for AC-DSSD and  $~\sim 130~\mu A$  for DC-DSSD at around 70 V

 Bulk capacitance : 256 pF for AC-DSSD, 35 pF for DC-DSSD, and 25 pF for PIN at around 70 V

## **Readout Electronics**

![](_page_18_Picture_1.jpeg)